ESP-WROOM-S2 Datasheet



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About This Guide

This document introduces the specifications of ESP-WROOM-S2 hardware, including the following topics.

Chapter	Title	Subject
Chapter 1	Overview	Introduction to ESP-WROOM-S2, including dimensions and specifications.
Chapter 2	Pin Description	Introduction to pin layout and the relevant description.
Chapter 3	Functional Description	Description of the major functional modules integrated on the ESP-WROOM-S2, including CPU, flash, memory and interfaces.
Chapter 4	Electrical Characteristics	Electrical data of ESP-WROOM-S2.
Chapter 5	Schematics	ESP-WROOM-S2 schematics and ESP-WROOM-S2 peripheral schematics.
Appendix A	Learning Resources	ESP8266-related must-read documents and must-have resources.

Release Notes

Date	Version	Release notes
2016.06	V1.0	First release.
2016.08	V1.1	Updated the operating temperature range; Added NCC Wi-Fi standard; Updated Section 3.4 "Interface Description".
2016.11	V1.2	Added Appendix—Learning Resources; Added "ESP-WROOM-S2 Peripheral Schematics" in Chapter 5.
2016.12	V1.3	Changed the minimum working voltage from 3.0V to 2.5V; Changed the power consumption during Deep-sleep from 10 μA to 20 μA .
2017.02	V1.4	Changed the maximum operating temperature of crystal oscillator from 85°C to 70°C, and added the description about the storage temperature range of crystal oscillator in Section 3.3.

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1.

Overview

Espressif provides the SMD module—ESP-WROOM-S2 that integrates ESP8266EX. The module has been adjusted to achieve the best RF performance. We recommend using ESP-WROOM-S2 for tests or for further development.

Note:

For more information on ESP8266EX, please refer to ESP8266EX Datasheet.

The module size is 16 mm x 23 mm x 3 mm (see Figure 1-1). The flash used on this module is a 2-MB SPI flash connected to HSPI, with a package size of SOP 8-150 mil. The gain of the on-board PCB antenna is 2 dBi.

The ESP-WROOM-S2 works as the SDIO/SPI slave with the SPI speed of up to 8 Mbps.

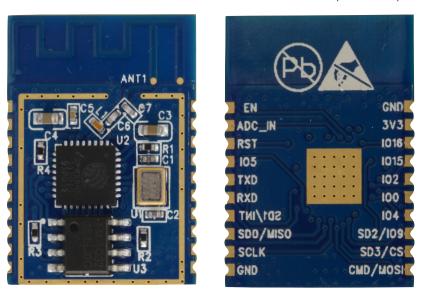


Figure 1-1. ESP-WROOM-S2 Module

Table 1-1. ESP-WROOM-S2 Specifications

Categories	Items	Specifications
	Standards	FCC/CE/TELEC/NCC
Wi-Fi	Wi-Fi protocols	802.11 b/g/n
	Frequency range	2.4 GHz ~ 2.5 GHz (2400M ~ 2483.5M)
	Peripheral interface	UART/I2C/GPIO/PWM/SDIO/SPI/IR Remote Control/ADC
	1 onphoral interface	GPIO/PWM

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Categories	Items	Specifications
	Operating voltage	2.5V ~ 3.6V
Hardware	Operating current	Average: 80 mA
riaraware	Operating temperature range	-40°C ~ 85°C
	Storage temperature	-40°C ~ 85°C
	Package size	16 mm x 23 mm x 3 mm
	External interface	-
	Wi-Fi mode	Station/SoftAP/SoftAP + Station
	Security	WPA/WPA2
	Encryption	WEP/TKIP/AES
Software	Firmware upgrade	UART Download / OTA (via network) / Download and burn firmware via host
	Software development	Supports Cloud Server Development SDK for secondary development
	Network protocols	IPv4, TCP/UDP/HTTP/FTP
	User configuration	AT Instruction Set, Cloud Server, Android/iOS app

Note:

ESP-WROOM-S2 with high temperature range option (-40 °C \sim 125 °C) is available for custom order.



2.

Pin Description

Figure 2-1 shows the pin distribution of ESP-WROOM-S2.

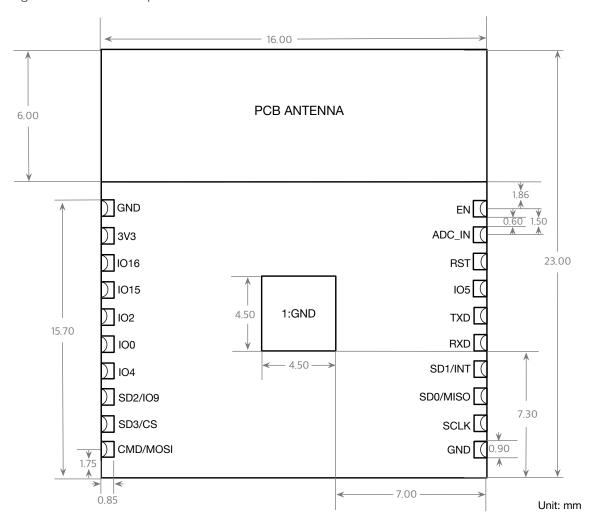


Figure 2-1. Top View of The ESP-WROOM-S2

Table 2-1. ESP-WROOM-S2 Dimensions

Length	Width	Height	PAD size (bottom)	Pin Pitch
16 mm	23 mm	3 mm	0.9 mm x 0.85 mm	1.5 mm

ESP-WROOM-S2 has 20 pins, please see the pin definitions in Table 2-2.



Table 2-2. ESP-WROOM-S2 Pin Definitions

No.	Pin Name	Functional Description
1	GND	Ground
		3.3V power supply (VDD)
2	3V3	Note:
		It is recommended the maximum output current a power supply provides be of 500 mA or above.
3	IO16	GPIO16; used for Deep-sleep wake-up when connected to RST pin.
		HSPICS
4	IO15	UART download: pull down.SDIO boot: floating (internal pull-up) or pull up.
		GPIO2; UART1_TXD
5	102	UART download: pull down.
		SDIO boot: don't-care.
		GPIO0
6	100	UART download: pull down.SDIO boot: don't-care.
7	104	GPIO4
8	SD2/IO9	SD_D2 (Series resistor: 100 \sim 200 Ω , 10 k pull-up resistor); GPIO9
9	SD3/CS	SD_D3 (Series resistor: 100 \sim 200 Ω , 10 k pull-up resistor); SLAVE_ SPI_CS
10	CMD/MOSI	SD_CMD (Series resistor: 100 \sim 200 Ω , 10 k pull-up resistor); SLAVE_ SPI_MOSI
11	GND	Ground
12	SCLK	SD_CLK (Series resistor: 100 ~ 200 Ω); SLAVE_ SPI_CLK
13	SD0/MISO	SD_D0 (Series resistor: 100 \sim 200 $\Omega,$ 10 k pull-up resistor); SLAVE_ SPI_MISO
14	SD1/INT	SD_D1 (Series resistor: 100 \sim 200 $\Omega,$ 10 k pull-up resistor); SLAVE_ SPI_INT
15	RXD	UARTO_RXD, receive end in UART download; GPIO3
16	TXD	UARTO_TXD, transmit end in UART download, floating (internal pull-up) or pull up; GPIO1
17	IO5	GPIO5
18	RST	Reset
19	ADC_IN	Tests the power-supply voltage of VDD3P3 and the input power voltage of TOUT. These two functions cannot be used simultaneously.
20	EN	Chip enable pin (cannot be floating). Active high.



Functional Description

3.1. MCU

ESP8266EX contained in the ESP-WROOM-S2 integrates Tensilica L106 32-bit microcontroller (MCU) and a 16-bit RSIC. The CPU clock speed is 80 MHz and can reach a maximum value of 160 MHz. The system can readily run a Real Time Operating System (RTOS). Currently, the Wi-Fi stack only takes up 20% of CPU time. The remaining CPU time (80% of total MIPS) can be used for user applications. The MCU can work in conjunction with the other parts of the chip through the following interfaces.

- Programmable RAM/ROM interface (iBus) that connects to the memory controller and can access the external flash.
- Data RAM interface (dBus) that connects to memory controller.
- AHB interface that accesses the register.

3.2. Memory

3.2.1. Internal SRAM and ROM

ESP8266EX Wi-Fi SoC integrates the memory controller including ROM and SRAM. MCU can access the memory controller through iBus, dBus, and AHB interfaces. All these interfaces can access ROM or RAM units. A memory arbiter determines the running sequence in the arrival order of requests.

According to our current version of SDK, SRAM space available to users is assigned as follows.

- RAM size < 50 kB, that is, when ESP8266EX is working in Station mode and connects to the router, available space in the Heap + Data sector is around 50 kB.
- There is no programmable ROM in ESP8266EX, therefore, user program must be stored in the SPI flash integrated into the ESP-WROOM-S2.

3.2.2. SPI Flash

ESP8266EX supports SPI flash. Theoretically speaking, ESP8266EX can support an up-to-16-MB SPI flash.

ESP-WROOM-S2 currently integrates a 2-MB SPI flash. ESP-WROOM-S2 supports these SPI modes: Standard SPI, DIO (Dual I/O), DOUT (Dual Output), QIO (Quad I/O) and QOUT (Quad Output).

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Please use the most updated download tool and configure SPI MODE in the download tool as DIO or DOUT.

3.3. Crystal Oscillator

ESP-WROOM-S2 uses a 26 MHz crystal oscillator. The accuracy of the crystal oscillator should be ± 10 PPM. The operating temperature range is -20°C to 70°C; and the storage temperature range is -40°C to 85°C.

When using the download tool, please note to select the right crystal oscillator type. In circuit design, capacitors C1 and C2 which connect to the earth are added to the input and output terminals of the crystal oscillator respectively. The values of the two capacitors can be flexible, ranging from 6 pF to 22 pF, however, the specific capacitive values depend on further testing of, and adjustment to, the overall performance of the whole circuit. Normally, the capacitive values of C1 and C2 are within 10 pF for the 26 MHz crystal oscillator.

The crystal oscillator should be placed as close to the XTAL pins as possible (without the traces being too long). It is good practice to add high density ground vias around the clock trace for great insulation.

There should be no vias on the input and output traces, which means the traces cannot cross layers.

Place the input and output bypass capacitors on the near left or right side of the chip. Do not place them on the traces.

Do not route high-frequency digital signal lines in the four-layer board. It is best not to route any signal line under the crystal oscillator. The larger the copper area on the top layer is, the better. As crystal oscillator is a sensitive component, do not place magnetic components such as high current inductor nearby.

3.4. Interface Description

Table 3-1. Interface Description

Interface	Pin	Functional Description	
SPI	GPIO12/13/14/15 or GPIO6/7/8/11	S2 can control SPI Slave as a Master or communicate with Host MCU as a Slave. In overlap mode, S2 can share the SPI interface with Flash, shifted by different CS signals.	
PWM	Any available GPIO (EXCEPT GPIO16)	Currently the demo provides four PWM channels (users can extend to six channels). PWM interface can realize the control of LED lights, buzzers, relays, electronic machines, etc.	

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Interface	Pin	Functional Description
IR	Any available GPIO (EXCEPT GPIO16)	The functionality of the infrared remote control interface can be realized via software programming. The interface uses NEC coding, modulation, and demodulation. The frequency of the modulated carrier signal is 38 kHz.
ADC	TOUT	Tests the power supply voltage of VDD3P3 (Pin3 and Pin4) and the input power voltage of TOUT (Pin6). However, these two functions cannot be used simultaneously. This interface is typically used in sensors.
I2C	Any available GPIO (EXCEPT GPIO16)	Connects to external sensors and display screens, etc.
UART	UARTO: TXD(U0TXD), RXD(U0RXD) UART1: IO2(TXD)	Communicates with UART device. Downloading: U0TXD + U0RXD or GPIO2 + U0RXD Communicating (UART0): U0TXD, U0RXD Debugging: UART1_TXD (GPIO2) can be used to print debugging information.



4. Electrical Characteristics

Note:

Unless otherwise specified, measurements are based on VDD = 3.3V, TA = 25°C.

4.1. Absolute Maximum Ratings

Table 4-1. Absolute Maximum Ratings

Rating	Condition	Value	Unit
Storage temperatue	-	-40 ~ 125	°C
Maximum soldering temperature	-	260	°C
Supply voltage	IPC/JEDEC J-STD-020	2.5 ~ 3.6	V

4.2. Recommended Operating Conditions

Table 4-2. Recommended Operating Conditions

Operating condition	Symbol	Min	Тур	Max	Unit
Operating temperature	-	-40	20	125	°C
Supply voltage	VDD	2.5	3.3	3.6	V

4.3. Digital Terminal Characteristics

Table 4-3. Digital Terminal Characteristics

Terminals	Symbol	Min	Тур	Max	Unit
Input logic level low	VIL	-0.3	-	0.25 VDD	V
Input logic level high	VIH	0.75 VDD	-	VDD + 0.3	V
Output logic level low	Vol	N	-	0.1 VDD	V
Output logic level high	Vон	0.8 VDD	-	N	V

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4.4. RF Performance

Table 4-4. RF Performance

Description	Min	Тур	Max	Unit
Input frequency	2400	-	2483.5	MHz
Input impedance	-	50	-	ohm
Input reflection	-	-	-10	dB
PA output power at 72.2 Mbps	15.5	16.5	17.5	dBm
PA output power in 11b mode	19.5	20.5	21.5	dBm
Sensitivity				
CCK, 1 Mbps	-	-98	-	dBm
CCK, 11 Mbps	-	-91	-	dBm
6 Mbps (1/2 BPSK)	-	-93	-	dBm
54 Mbps (3/4 64-QAM)	-	-75	-	dBm
HT20, MCS7 (65 Mbps, 72.2 Mbps)	-	-72	-	dBm
Adjacent channel rejection				
OFDM, 6 Mbps	-	37	-	dB
OFDM, 54 Mbps	-	21	-	dB
HT20, MCS0	-	37	-	dB
HT20, MCS7	-	20	-	dB

4.5. Sensitivity

Table 4-5. Sensitivity

Parameters	Min	Тур	Max	Unit
Input frequency	2412	-	2484	MHz
Input impedance	-	50	-	Ω
Input reflection	-	-	-10	dB
PA output power at 72.2 Mbps	15.5	16.5	17.5	dBm
PA output power in 11b mode	19.5	20.5	21.5	dBm
Sensitivity				
DSSS, 1 Mbps	-	-98	-	dBm



Parameters	Min	Тур	Max	Unit
CCK, 11 Mbps	-	-91	-	dBm
6 Mbps (1/2 BPSK)	-	-93	-	dBm
54 Mbps (3/4 64-QAM)	-	-75	-	dBm
HT20, MCS7 (65 Mbps, 72.2 Mbps)	-	-72	-	dBm
Adjacent channel rejection				
OFDM, 6 Mbps	-	37	-	dB
OFDM, 54 Mbps	-	21	-	dB
HT20, MCS0	-	37	-	dB
HT20, MCS7	-	20	-	dB

4.6. Power Consumption

The following power consumption data were obtained from the tests with a 3.3V power supply and a voltage stabilizer, in 25°C ambient temperature.

- All tests were performed at the antenna port without SAW filter.
- All data are based on 90% duty cycle in continuous transmission mode.

Table 4-6. Power Consumption

Modes	Min	Тур	Max	Unit
Tx 802.11b, CCK 11 Mbps, Pout = +17 dBm	-	170	-	mA
Tx 802.11g, OFDM 54 Mbps, Pout = +15 dBm	-	140	-	mA
Tx 802.11n, MCS7, Pout = +13 dBm	-	120	-	mA
Rx 802.11b, 1024 bytes packet length , -80 dBm	-	50	-	mA
Rx 802.11g, 1024 bytes packet length , -70 dBm	-	56	-	mA
Rx 802.11n, 1024 bytes packet length , -65 dBm	-	56	-	mA
Modem-sleep①	-	15	-	mA
Light-sleep②	-	0.9	-	mA
Deep-sleep③	-	20	-	μΑ
Power Off	-	0.5	-	μΑ

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Notes:

- ① Modem-sleep is used when such applications as PWM or I2S require the CPU to be working. In cases where Wi-Fi connectivity is maintained and data transmission is not required, the Wi-Fi Modem circuit can be shut down to save power, according to 802.11 standards (such as U-APSD). For example, in DTIM3, when ESP8266EX sleeps for 300 ms and wakes up for 3 ms to receive Beacon packages from AP, the overall average current consumption is about 15 mA.
- ② Light-sleep is used for applications whose CPU may be suspended, such as Wi-Fi switch. In cases where Wi-Fi connectivity is maintained and data transmission is not required, Wi-Fi Modem circuit and CPU can be shut down to save power, according to 802.11 standards (such as U-APSD). For example, in DTIM3, when ESP8266EX sleeps for 300 ms and wakes up for 3 ms to receive Beacon packages from AP, the overall average current consumption is about 0.9 mA.
- ③ **Deep-sleep** is for applications that do not require Wi-Fi connectivity and only transmit data over long time lags, e.g., a temperature sensor that measures temperature every 100s. For example, when ESP8266EX sleeps for 300s then wakes up to connect to AP (taking about 0.3 ~ 1s), the overall average current consumption is far less than 1 mA. The current consumption of 20 μA was obtained at the voltage of 2.5V.

4.7. Reflow Profile

Table 4-7. Reflow Profile

Indicator	Value
Ramp-up Rate (Ts Max to TL)	3°C/second max.
Preheat	
Temperature Min. (T _S Min.)	150°C
Temperature Typ. (Ts Typ.)	175°C
Temperature Min. (T _S Max.)	200°C
Time (Ts)	60 ~ 180 seconds
Ramp-up Rate $(T_L \text{ to } T_P)$	3°C/second max.
Time maintained above: Temperature (T_L)/Time (T_L)	217°C/60 ~ 150 seconds
Peak temperature (T _P)	260°C max, for 10 seconds
Target Peak Temperature (TP Target)	260°C + 0/-5°C
Time within the actual Peak Temperature of 5°C (T _P)	20 ~ 40 seconds
T_S max to T_L (Ramp-down Rate)	6°C/second max.
Time from 25°C to Peak Temperature (t)	8 minutes max.

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5.

Schematics

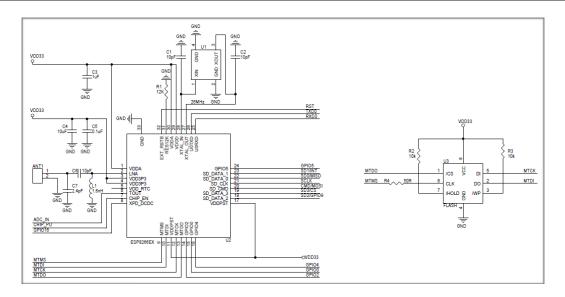


Figure 5-1. ESP-WROOM-S2 Schematics

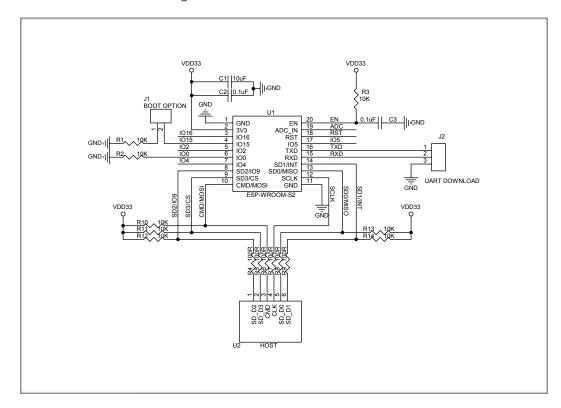


Figure 5-2. ESP-WROOM-S2 Peripheral Schematics



Α.

Appendix — Learning Resources

A.1. Must-Read Documents

ESP8266 Quick Start Guide

Description: This document is a quick user guide to getting started with ESP8266. It includes an introduction to the ESP-LAUNCHER, how to download firmware on to the board and run it, how to compile the AT application, structure and the debugging method of RTOS SDK. Basic documentation and other related resources for the ESP8266 are also provided.

• ESP8266 SDK Getting Started Guide

Description: This document takes ESP-LAUNCHER and ESP-WROOM-02 as examples to introduce how to use ESP8266 SDK. The contents include preparations before compilation, SDK compilation and firmware download.

ESP-WROOM-02 PCB Design and Module Placement Guide

Description: The ESP-WROOM-02 module is designed to be soldered to a host PCB. This document compares six different placements of the antenna on a host board and provides notes on PCB design.

• ESP8266 Hardware Resources

Description: This zip package includes manufacturing specifications of the ESP8266 board and the modules, manufacturing BOM and schematics.

ESP8266 AT Command Examples

Description: This document introduces some specific examples of using Espressif AT commands, including single connection as a TCP client, UDP transmission and transparent transmission, and multiple connection as a TCP server.

• ESP8266 AT Instruction Set

Description: This document provides lists of AT commands based on ESP8266_NONOS_SDK, including user-defined AT commands, basic AT commands, Wi-Fi AT commands and TCP/IP-related AT commands. It also introduces the downloading of AT firmware into flash.

TCP/UDP UART Passthrough Test Demonstration

Description: This guide is intended to help users run a TCP & UDP passthrough test on the ESP8266 IoT platform.

FAQ



A.2. Must-Have Resources

• ESP8266 SDKs

Description: This website page provides links to the latest version of ESP8266 SDK and the older ones.

• ESP8266 Tools

Description: This website page provides links to the ESP8266 flash download tools and ESP8266 performance evaluation tools.

- ESP8266 APK
- ESP8266 Certification and Test Guide
- ESP8266 BBS
- ESP8266 Resources



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